

FEATURES

■ LOW INTERMODULATION DISTORTION

IM3=-45 dBc at Pout= 36.5dBm

Single Carrier Level

■ HIGH POWER

P1dB=48.0dBm at 5.3GHz to 5.9GHz

■ HIGH GAIN

G1dB=9.0dB at 5.3GHz to 5.9GHz

■ BROAD BAND INTERNALLY MATCHED FET

■ HERMETICALLY SEALED PACKAGE

RF PERFORMANCE SPECIFICATIONS (Ta= 25°C)

CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Output Power at 1dB Gain Compression Point	P1dB	VDS=10V f = 5.3 to 5.9GHz IDSset=9.5A	dBm	47.0	48.0	—
Power Gain at 1dB Gain Compression Point	G1dB		dB	8.0	9.0	—
Drain Current	IDS1		A	—	13.2	15.0
Gain Flatness	ΔG		dB	—	—	± 0.8
Power Added Efficiency	η_{add}		%	—	42	—
3rd Order Intermodulation Distortion	IM3	Two-Tone Test Po=36.5dBm (Single Carrier Level)	dBc	-42	-45	—
Drain Current	IDS2		A	—	—	11.8
Channel Temperature Rise	ΔT_{ch}	(VDS X IDS +Pin-P1dB) X Rth(c-c)	°C	—	—	100

Recommended Gate Resistance(Rg) : 28 Ω (Max.)

ELECTRICAL CHARACTERISTICS (Ta= 25°C)

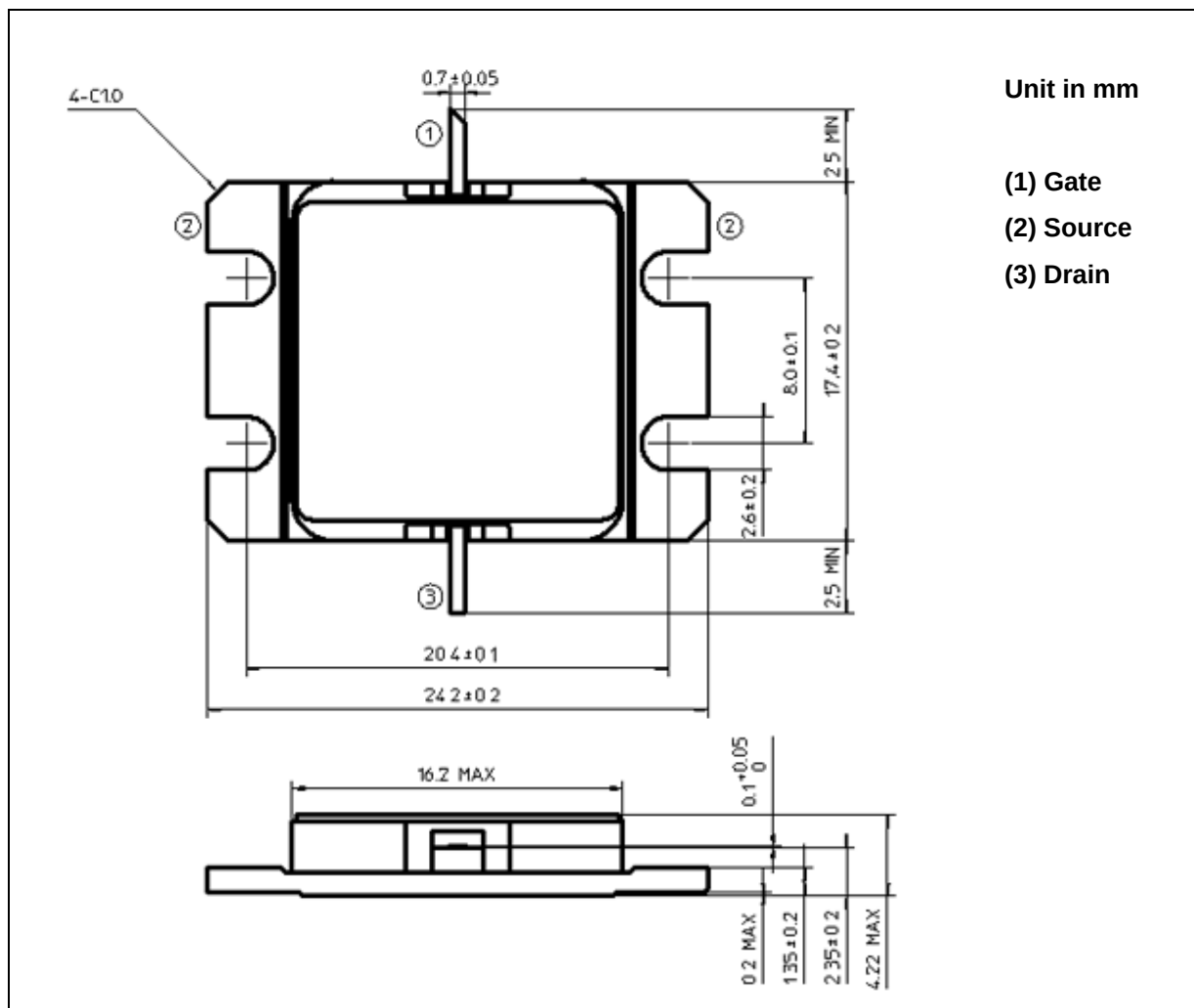
CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Transconductance	gm	VDS= 3V IDS= 12.0A	S	—	20	—
Pinch-off Voltage	VGSoff	VDS= 3V IDS= 200mA	V	-1.0	-1.8	-3.0
Saturated Drain Current	IDSS	VDS= 3V VGS= 0V	A	—	38	—
Gate-Source Breakdown Voltage	VGSO	IGS= -1.0mA	V	-5	—	—
Thermal Resistance	Rth(c-c)	Channel to Case	°C/W	—	0.6	0.8

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ABSOLUTE MAXIMUM RATINGS (Ta= 25°C)

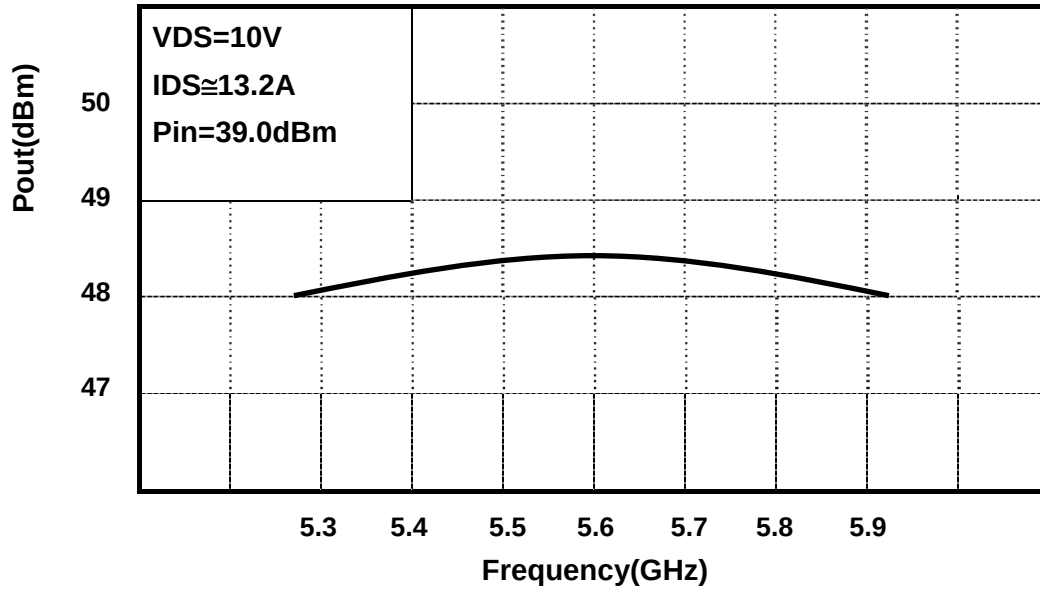
CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain-Source Voltage	VDS	V	15
Gate-Source Voltage	VGS	V	-5
Drain Current	IDS	A	20
Total Power Dissipation (Tc= 25 °C)	PT	W	187.5
Channel Temperature	Tch	°C	175
Storage Temperature	Tstg	°C	-65 to +175

PACKAGE OUTLINE (2-16G1B)**HANDLING PRECAUTIONS FOR PACKAGE MODEL**

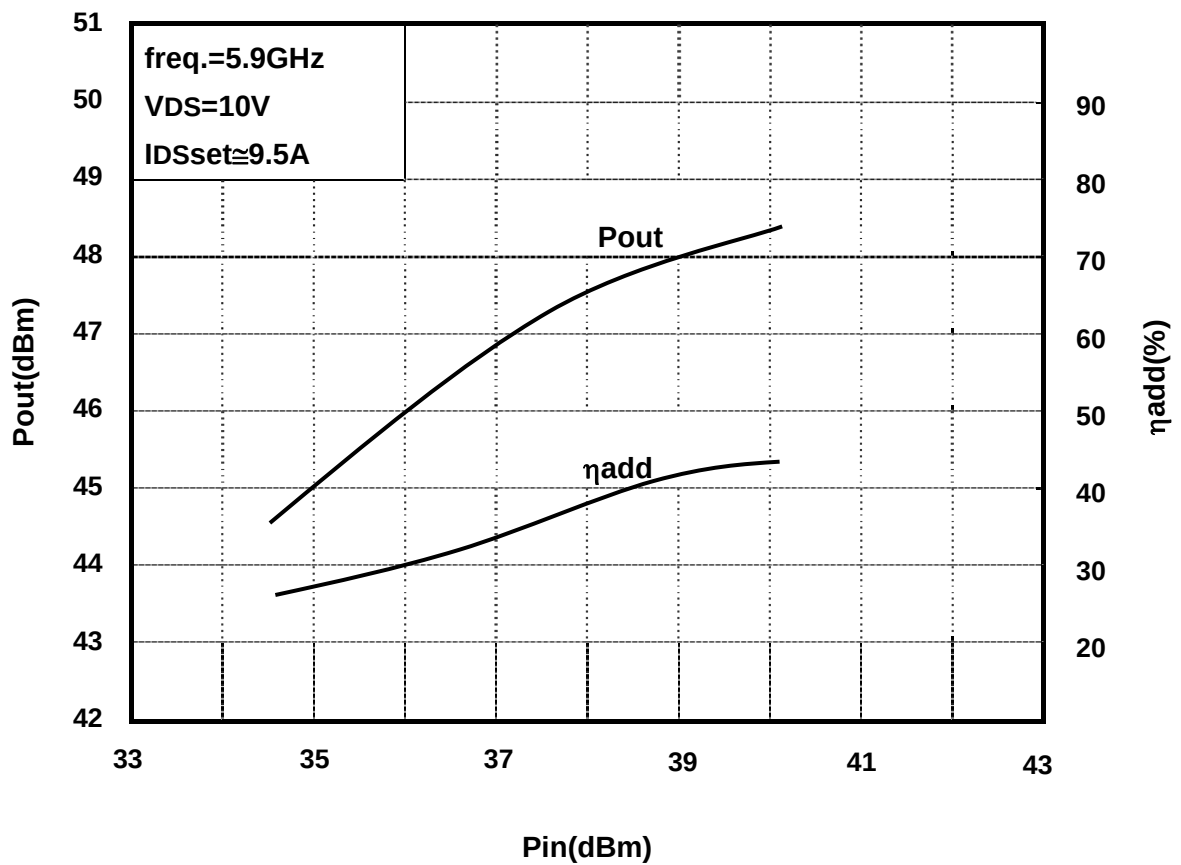
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

RF PERFORMANCE

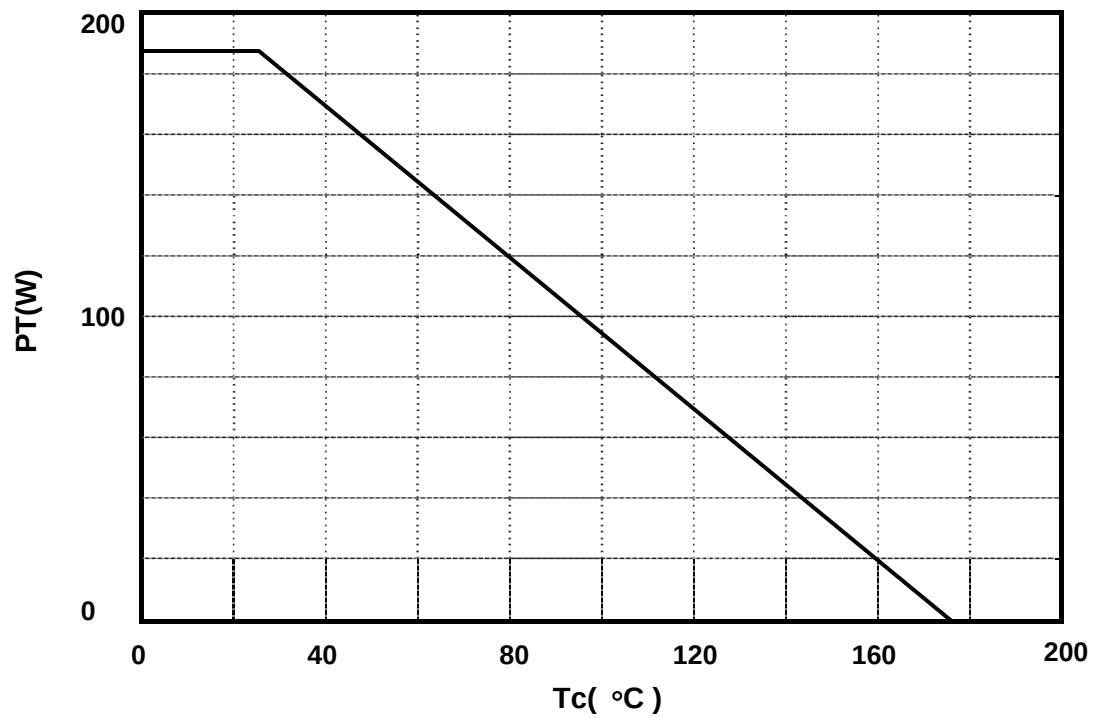
Output Power (Pout) vs. Frequency



Output Power(Pout) vs. Input Power(Pin)



Power Dissipation(PT) vs. Case Temperature(Tc)



IM3 vs. Power Characteristics

